Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20030160312").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/08/04 11:25
S1	11	(("20030062614") or ("20030148597") or ("5506753") or ("5909058") or ("6002165") or ("6060774") or ("6184064") or ("6208521") or ("6225695") or ("6297548") or ("6433418")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/04/24 15:27
S2	19761	((438/612,109) or (257/688,691,693, 723,737,780,696,727,686,712,666)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/04/04 09:57
S3	14516	S2 and @pd<"20030330"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 09:57
S4	336	S3 and (stacked adj (die or dice or chip))	US-PGPUB; USPAT; USOCR;	OR	ON	2006/04/04 10:07
	* .		EPO; JPO; IBM_TDB	, ,		
S5	61	S4 and spacer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:07
S6	5	S5 and ("active circuity" or "flash memory array" or "logic circuitry")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:08
S7	2034	(stacked adj (die or dice or chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:07
S8	336	S7 and spacer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:49

S9	10	S8 and ("active circuity" or "flash memory array" or "logic circuitry")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 10:37
S10	393	S7 and (spacer or "support structure")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:48
S11	76	S7 and ("support structure")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:49
S12	55	S7 and (spacer near5 silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:50
S13	8	S7 and ("support structure" near5 silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/04 10:49
S14	1	("2003/0111716").URPN.	USPAT	OR -	ON	2006/04/04 11:09
S15	348	"bonding pad" near size	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/21 13:31
S16	21	S15 and spacer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/21 13:10
S17	0	"bonding pad" near "1mm"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/21 13:30
S18	0	"bonding pad" near "1 mm"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/21 13:30

S19	. 0	"bonding pad" near "1000 micron"	US-PGPUB; USPAT;	OR	ON	2006/04/21 13:51
-			USOCR; EPO; JPO; IBM_TDB			
S20	0	"bonding pad" near "die edge"	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2006/04/21 13:31
	*	•	IBM_TDB			ė.
521	1014	"bonding pad" near5 size	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/21 13:31
S22	288	"bonding pad" adj3 size	US-PGPUB;	OR	ON	2006/04/21 13:39
-8			USPAT; USOCR;		. (8)	Υ.
-	-		EPO; JPO; IBM_TDB	: %		* *
S23	0	"bonding pad" near "300 micrometer"	US-PGPUB;	OR	ON	2006/04/21 13:51
		·	USPAT; USOCR; EPO; JPO;			
			IBM_TDB		0.1	2006/04/24 45:27
S24	1	10/790907	US-PGPUB; USPAT; USOCR;	OR	ON	2006/04/21 15:37
			EPO; JPO; IBM_TDB			
S25	19840	((438/612,109) or (257/688,691,693, 723,737,780,696,727,686,712,666)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/04/24 10:37
S26	14516	S25 and @pd<"20030330"	US-PGPUB;	OR	ON	2006/04/24 10:37
			USPAT; USOCR;			
			EPO; JPO; IBM_TDB			,
S27	336	S26 and (stacked adj (die or dice or chip))	US-PGPUB; USPAT; USOCR;	OR	ON	2006/04/24 10:37
			EPO; JPO; IBM_TDB			
S28	0	S27 and "flash memory array"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 10:37

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S29	32	S27 and "flash memory"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 10:38
S30	2	S25 and ((buss same memory) same (electronic adj system))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:14
S31	43522	(electronic adj system)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:14
S32	27	S31 and (memory near5 (coupled or attached) near5 buss)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:17
S33	1	S31 and ((flash adj memory) near5 (coupled or attached) near5 buss)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:18
S34	3673	S31 and ((flash adj memory))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:11
S35	9	S34 and ((coupled or attached) near5 buss)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:21
S36	1579	S31 and (buss)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:20
S37	10	S36 and ((flash adj memory) near10 (coupled or attached))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 11:21
S38	1	("6493861").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/04/24 15:28

S39	19840	((438/612,109) or (257/688,691,693, 723,737,780,696,727,686,712,666)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/04/24 15:40
S40	14516	S39 and @pd<"20030330"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 15:40
S41	336	S40 and (stacked adj (die or dice or chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 15:41
S42	336	S41 and (dummy (chip or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 15:41
S43	7	S41 and (dummy adj (chip or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 15:41
S44	87173	((flash adj memory))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:12
S45	44797	S44 and (bus or buss)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:12
S46	16742	S44 and (coupled adj3 (bus or buss))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	ÖR	ON	2006/04/24 16:12
S47	679	S46 and "electronic system"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:30
S48	111	S47 and "semiconductor device"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:31

S49	4	S48 and (electrically adj connected)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:13
S50	41	S48 and @pd<"20040329"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:31
S51	43522	"electronic system"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:30
S52	1074	S51 and (memory near5 (coupled adj3 (bus or buss)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:30
S53	137	S52 and "semiconductor device"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:31
S54	71	S53 and @pd<"20040329"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/24 16:31
S55		10/815966	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/04/25 09:28